<u>Tender for re-opening of 5-year HKD</u> <u>HKSAR Institutional Government Bonds</u> to be held on June 25

The following is issued on behalf of the Hong Kong Monetary Authority:

The Hong Kong Monetary Authority (HKMA), as representative of the Hong Kong Special Administrative Region Government (HKSAR Government), announced today (June 19) that a tender of 5-year HKD Government Bonds (Bonds) through the re-opening of existing 5-year Government Bond issue 05GB3005002 under the Infrastructure Bond Programme will be held on Wednesday, June 25, 2025, for settlement on Thursday, June 26, 2025.

An additional amount of HK\$1.25 billion of the outstanding 5-year Bonds (issue no. 05GB3005002) will be on offer. The Bonds will mature on May 15, 2030, and will carry interest at the rate of 2.70 per cent per annum payable semi-annually in arrear. The Indicative Pricings of the Bonds on June 19, 2025, are 101.75 with an annualised yield of 2.334 per cent.

Tender is open only to Primary Dealers appointed under the Infrastructure Bond Programme. Anyone wishing to apply for the Bonds on offer can do so through any of the Primary Dealers on the latest published list, which can be obtained from the Hong Kong Government Bonds website at www.hkgb.gov.hk. Each tender must be for an amount of HK\$50,000 or integral multiples thereof.

Tender results will be published on the HKMA's website, the Hong Kong Government Bonds website, Bloomberg (GBHK <GO>) and Refinitiv (IBPGSBPINDEX). The publication time is expected to be no later than 3pm on the tender day.

HKSAR Institutional Government Bonds Tender Information

Tender information of re-opening of 5-year HKD HKSAR Institutional Government Bonds:

Issue Number : 05GB3005002

Stock Code : 4293 (HKGB 2.70 3005)
Tender Date and . Wednesday, June 25, 2025

Time 9.30am to 10.30am

Issue and

Settlement Date : Thursday, June 26, 2025

Amount on Offer : HK\$1.25 billion

Maturity : 5 years

Remaining

maturity : Approximately 4.89 years

Maturity Date : Wednesday, May 15, 2030

Interest Rate

2.70 per cent p.a. payable semi-annually in arrear

May 15 and November 15 in each year, commencing on the Issue Date up to and

Interest Payment Dates

including the Maturity Date, subject to adjustment in accordance with the terms of the Institutional Issuances Information Memorandum of the Infrastructure Bond Programme and Government Sustainable Bond Programme (Information Memorandum) published on the Hong Kong Government

Bonds website.

Method of Tender : Competitive tender

Each competitive tender must be for an amount of HK\$50,000 or integral multiples thereof. Any tender applications for the Bonds must be submitted through a Primary Dealer on the latest published list. The accrued interest to be paid by successful bidders on the issue date (June

Tender Amount

: 26, 2025) for the tender amount is 155.34 per minimum denomination of HK\$50,000. (The accrued interest to be paid for tender amount exceeding HK\$50,000 may not be exactly equal to the figures calculated from the accrued interest per minimum

denomination of HK\$50,000 due to

rounding).

Please see the Information Memorandum Other Details : available on the Hong Kong Government

Bonds website or approach Primary Dealers.

Expected commencement date of dealing on the Stock Exchange of Hong Kong Limited

The tender amount is fully fungible with the existing 05GB3005002 (Stock code: 4293) listed on the Stock Exchange of Hong

Kong.

Use of Proceeds

institutional part of the Infrastructure Bond Programme. Proceeds will be invested : in infrastructure projects in accordance with the Infrastructure Bond Framework published on the Hong Kong Government

The Bonds will be issued under the

Bonds website.